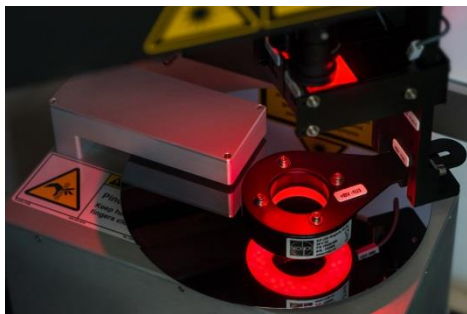




 Marking

IL 2000 (2" - 2000mm)

The InnoLas Wafer Marking System IL 2000
for the unique Identification of your wafers



Laser and Optics

Laser Type	Nd:YAG 355/532/1064 & CO ₂ 10.600nm
Laser Class	Class 1 / Class 4 with open cabinet
Focus Lens	F-Theta Objective
Galvo Head	High precision digitally controlled unit
Laser Stability	±1% peak to peak

Marking

Fonts	Dot Matrix SEMI OCR 5x9 / 10x18 / 15x27 Barcode SEMI BC412, IBM BC412 2D Code SEMI T7 Engraved Mode
Checksum	SEMI / IBM / customized (optional)
Serialization	Numeric / Alphanumeric / IBM
Text Position	Adjustable in X-, Y-Axis and Angle
Repeatability X and Y-direction	±75 µm (high precision) / ±100 µm (standard)
Dot Depth	0,1 – 100µm (depending on laser & material)
Dot Diameter	25 – 150 µm (depending on laser & material)

Handling System

Wafer Sizes	2 inch – 200 mm
Wafer Transfer	Single Arm Robot – Double End Effector
Wafer Alignment	Opto-mechanical
Wafer Handling	Vacuum / Edge Grip (optional)
Loading Stations	4
Throughput (wafers/hr)	180 (SEMI M13 spec. w/o reading)

Facility Requirements

Electrical	230 V (1P/1N/1PE) / 50 Hz / 16 Amps Optional: 115-200-240-370-380-400-420-480V
Power Consumption	1200 W
Communication	Ethernet RJ45 (SECS/GEM optional)
Vacuum	-800 mbar / 8mm OD connection
Exhaust	33,6 m ³ /hr / 50 mm ID connection
CDA – Compressed Dry Air	6 bar / 8mm OD connection
PFO – Process Fluid Outlet	8mm OD connection
Cooling Water (optional)	> 5 l/min at 15°C
Water Pressure	2-6 bar
Weight	750 kg
Dimension (w x l x h)	1275 x 1843 x 2027 mm

General

System Frame	Powder coated
System Panels	Powder coated
Mini Environment	n/a
Certification	CDRH #0010530 / CE